

Amendments to the Specification:

Please replace the paragraph beginning on page 7, lines 7, with the following amended paragraph:

The inventors have further found that an acid copper plating solution containing an organic acid or an inorganic acid at a concentration of 0.4 mol/l or more is useful to directly plate copper on a substrate of another metal such as Ta, Ti, Al, Ru, Pt, or Ir, without a copper seed film.